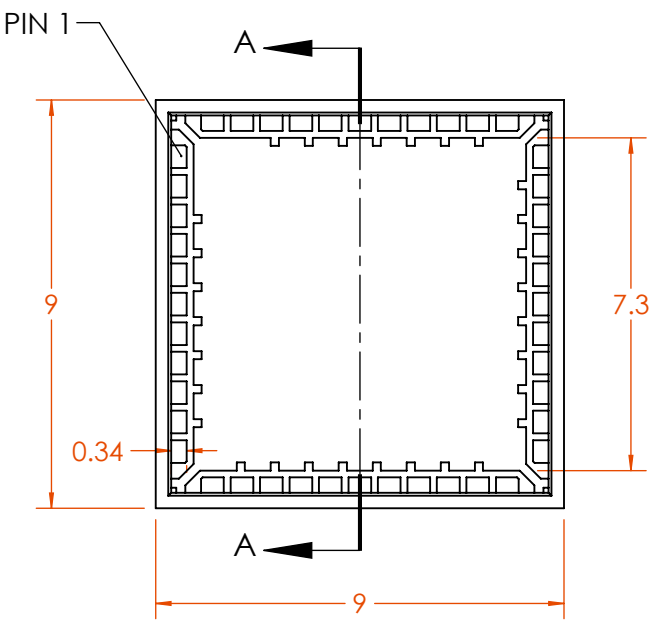
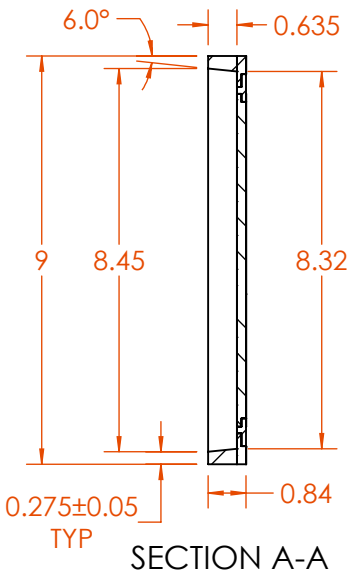
TOP VIEW

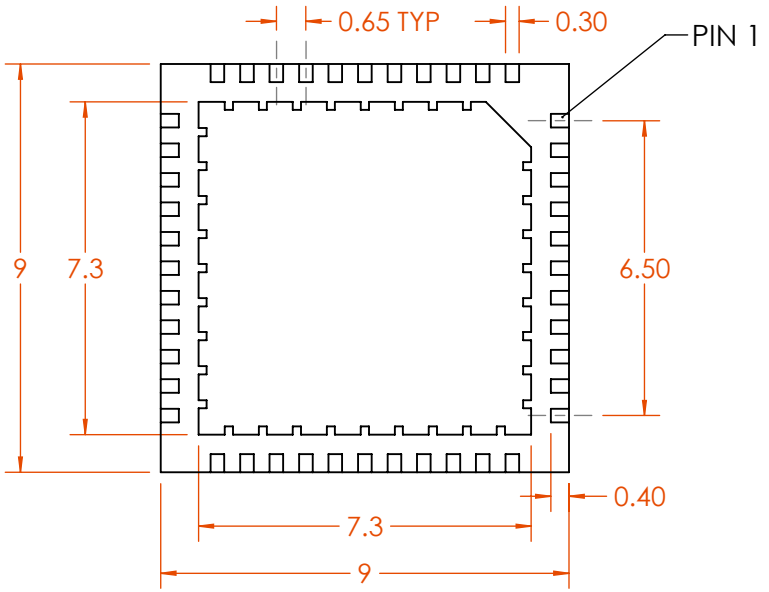


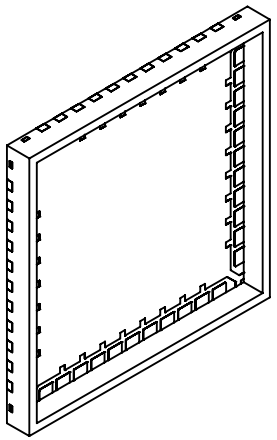

SIDE VIEW



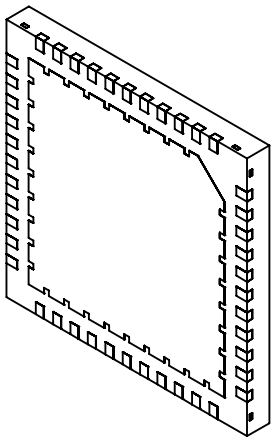

SECTION A-A

BOTTOM VIEW



ISOMETRIC VIEW OF CAVITY SIDE



ISOMETRIC VIEW OF PCB SIDE

Notes: (Unless Otherwise Specified)
1) BODY; PLASTIC, SEMICONDUCTOR GRADE
2) LEAD FRAME: COPPER, C-194F/H
3) LEAD FRAME PLATING: Ni, Pd, Au
4) FRAME THICKNESS: 0.203mm
5) DIE PAD: 7.3 X 7.3mm
6) JEDEC OUTLINE: MO-220

| TOLERANCES UNLESS NOTED | |
|---|---|
| X.X | ± 0.05 |
| X.XX | ± 0.01 |
| X.XXX | ± 0.005 |
| X.XXXX | ± 0.0005 |

ALL DIMENSIONS IN

☐ INCHES ☒ MILLIMETERS

THIRD ANGLE PROJECTION

| APPROVALS | DATE |
|---|---|
| DRAWN JMG | 05/07/13 |
| CHECKED | |
| ENG APPR. | |
| MFG APPR. | |
| Q.A. | |
| CUST. | |
| REVISED | |

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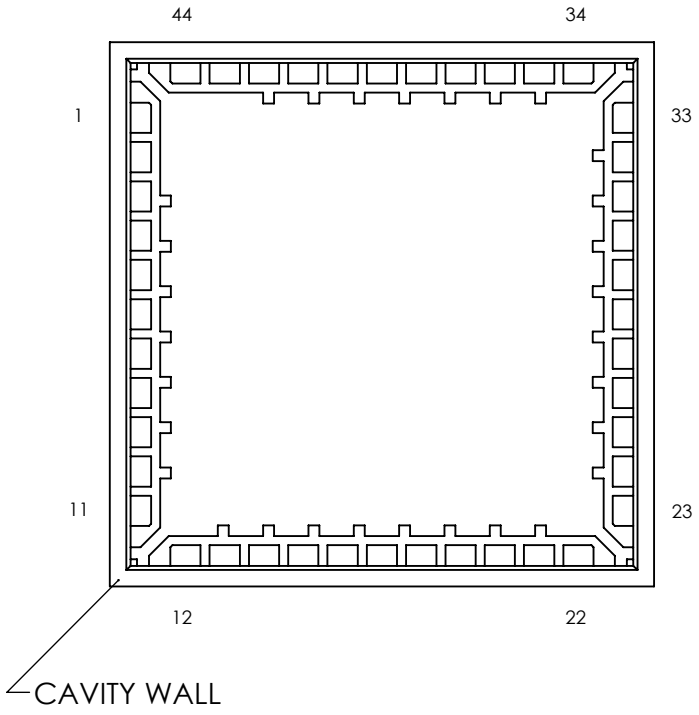
TITLE:

# 44-LEAD 9mm P=0.65mm QFN CAVITY PACKAGE

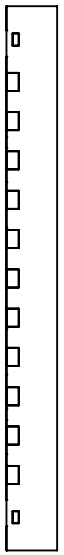
| SCALE | SIZE | DWG. NO. | REV |
|---|---|---|---|
| 6:1 | A | 464570 M-QFN44W.65-9MM-G7 | A |

DO NOT SCALE DRAWING | SHEET 1 OF 4

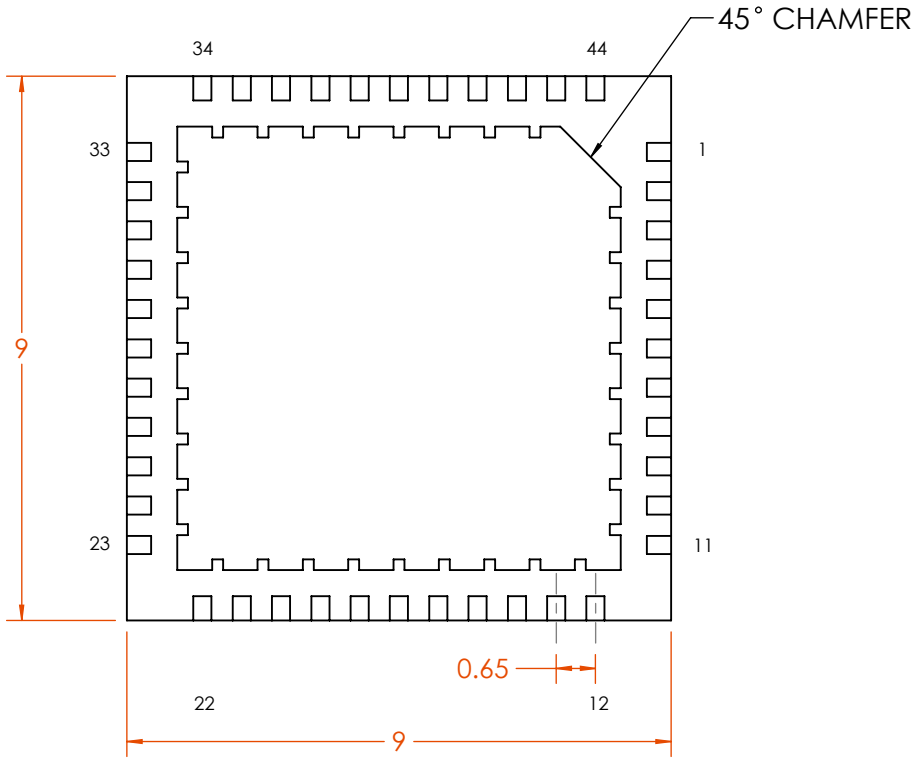
TOP VIEW




SIDE VIEW
(BEFORE LID ATTACH)



BOTTOM VIEW

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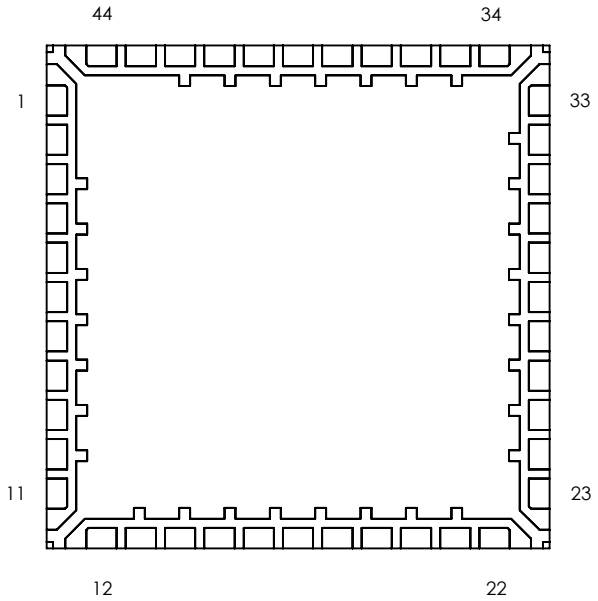
TITLE:

# 44-LEAD 9mm P=0.65mm QFN CAVITY PACKAGE LEAD NUMBERING

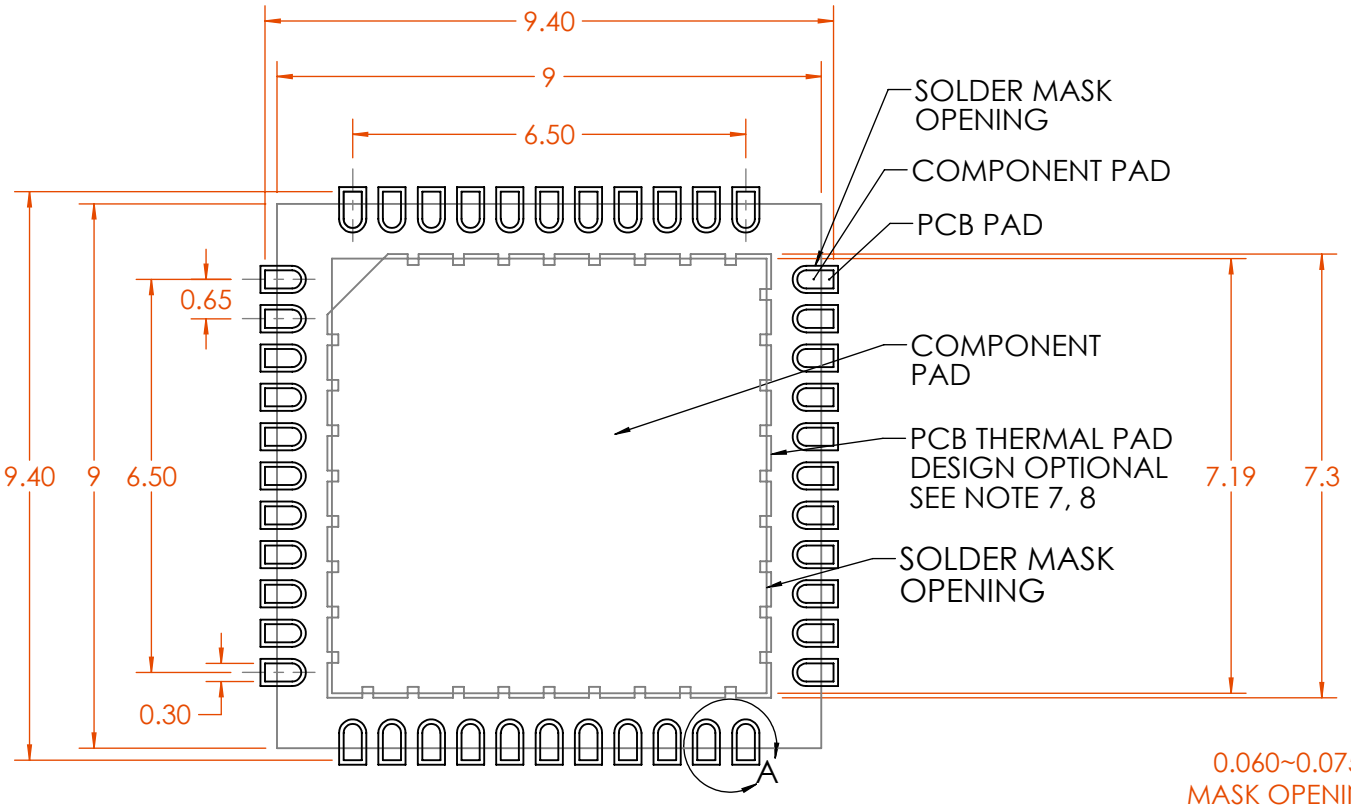
| SCALE | SIZE | DWG. NO. | REV |
|---|---|---|---|
| 8:1 | A | 464570 M-QFN44W.65-9MM-G7 | A |

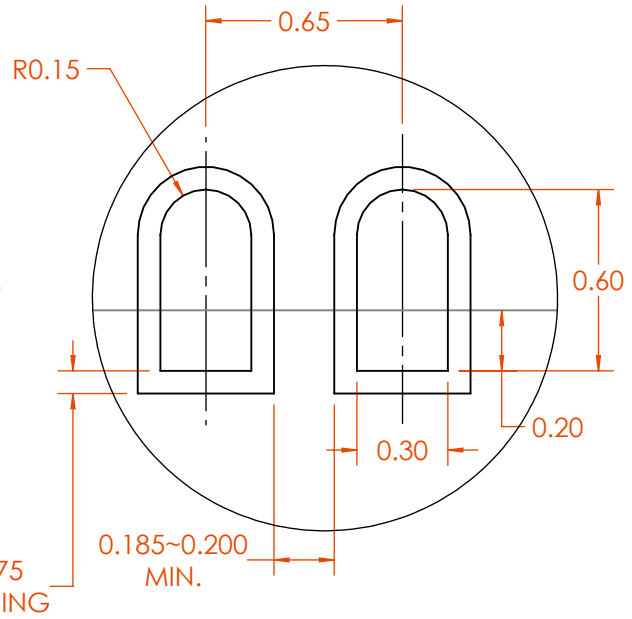
DO NOT SCALE DRAWING | SHEET 2 OF 4

# BOND DIAGRAM




| | | | |
|---|---|---|---|
| Mirror Semiconductor™ | | www.MirrorSemi.com | |
| TITLE: 44-LEAD 9mm P=0.65mm QFN CAVITY PACKAGE BOND DIAGRAM | | | |
| SCALE **8:1** | SIZE **A** | DWG. NO. **464570 M-QFN44W.65-9MM-G7** | REV A |
| DO NOT SCALE DRAWING | | SHEET 3 OF 4 | |




DETAIL A
SCALE 40 : 1

Notes: (Unless Otherwise Specified).

1. DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN KNOWLEDGE BASE WHEN DESIGNING THE PCB.
2. SURROUND EACH SIDE OF I/O PERIMETER PADS WITH 0.060~0.075 mm (2.4~3.0mils) NSMD SOLDER MASK OPENING. OPTIONALLY OK TO USE RECTANGLE (NSMD) MASK OPENING AROUND I/O PADS.
3. ROUNDED PCB LAND PADS REDUCE SOLDER BRIDGING. PAD CHAMFER ANGLE MAY VARY.
4. PCB LANDS SHOULD BE 0.2mm LONGER THAN THE PACKAGE I/O PADS.
5. THE WIDTH OF PERIMETER PCB PADS SHOULD MATCH (1:1) THE WIDTH OF THE PACKAGE PADS.
6. REFER TO INDUSTRY REFERENCES SUCH AS IPC-SM-782 FOR PCB LAND PATTERN DESIGN.
7. THERMAL GROUND PADS MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
   - A. MAKE COPPER THERMAL PAD AS LARGE AS POSSIBLE.
   - B. DRILL MULTIPLE THERMAL VIAS 0.25~0.33mm DIAMETER USING 0.8~1.2mm PITCH GRID.
   - C. PLATE THERMAL VIA BARRELS WITH 1-OUNCE COPPER (18µm).
   - D. TENT (COVER) THERMAL VIAS WITH SOLDER MASK 0.1mm LARGER THAN THE VIA DIAMETER.
8. STENCIL DESIGN MAY BE CHANGED TO SUITE REQUIREMENTS OF THE DESIGNER.
   - A. LASER CUT STENCIL 0.125mm (5mil) THICK. APERTURE SIZE-TO-LAND RATIO OF 1:1.
   - B. THE SOLDER PASTE OPENING IN THE THERMAL PAD AREA SHOULD BE A MATRIX ARRAY OF SMALLER APERATURES INSTEAD OF ONE LARGE APERATURE TO CONTROL PASTE AMOUNTS.
   - C. APPLY 50% TO 80% SOLDER PASTE COVERAGE IN THE PAD AREA.

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TITLE: 44-LEAD 9mm P=0.65mm QFN CAVITY PACKAGE RECOMMENDED PCB LAYOUT

| SCALE | SIZE | DWG. NO. | REV |
|---|---|---|---|
| 8:1 | A | 464570 M-QFN44W.65-9MM-G7 | A |

DO NOT SCALE DRAWING | SHEET 4 OF 4